

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

A marked-up version of each of the presently amended claims, highlighting the changes thereto, follows:

12. (Twice Amended) A method of manufacturing a multichip module system comprising:
forming a substrate for use in said multichip module system, the substrate having at least first and second positions thereon, the at least first and second positions for locating a first and second semiconductor device thereat, and having at least one other vacant position for locating a third semiconductor device thereat on the substrate;
installing said first and second semiconductor devices in the respective at least first and second positions of the substrate, the first and second semiconductor devices each having (a) the same predetermined performance capability;
determining if the multichip module system has an unacceptable semiconductor device thereon;
disabling circuitry connected to the unacceptable semiconductor device; and
repairing the substrate to have an acceptable semiconductor device thereon by installing a third semiconductor device in the at least one other vacant position in the substrate, the third semiconductor device installed in the at least one other vacant position having said predetermined performance capability.